



Material Content Data Sheet



Sales Product Name		2EDL05I06BF		Issued		22. January 2018		
MA#		MA002055074						
Package		PG-DSO-8-70		Weight*		75.08 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.952	1.27	1.27	12682	12682
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		105	
	non noble metal	zinc	7440-66-6	0.031	0.04		418	
	non noble metal	iron	7439-89-6	0.628	0.84		8365	
wires	non noble metal	copper	7440-50-8	25.502	33.97	34.86	339668	348556
	noble metal	palladium	7440-05-3	0.000	0.00		5	
	non noble metal	copper	7440-50-8	0.040	0.05	0.05	533	538
encapsulation	organic material	carbon black	1333-86-4	0.232	0.31		3091	
	plastics	epoxy resin	-	6.265	8.34		83447	
	inorganic material	silicondioxide	60676-86-0	39.912	53.16	61.81	531587	618125
leadfinish	non noble metal	tin	7440-31-5	0.833	1.11	1.11	11100	11100
plating	noble metal	silver	7440-22-4	0.134	0.18	0.18	1779	1779
glue	plastics	acrylic resin	-	0.119	0.16		1588	
	noble metal	silver	7440-22-4	0.423	0.56	0.72	5632	7220
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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